

07-20-2000



FORM PTO-1595

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U.S. DEPARTMENT OF COMMERCE

1/31/92

101409176

Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please Record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
 SEIICHI WATANABE  
 KENJI SHINOAZAKI  
 MINORU KOHNO  
 HIROYUKI MITSUHASHI  
 MINEHIRO TONOSAKI  
 MASATO KOBAYASHI  
 Additional name(s) of conveying party(ies) attached?  
 Yes  No

2. Name and address of receiving party(ies):  
 Name: Sony Corporation  
 Internal Address: \_\_\_\_\_  
 \_\_\_\_\_  
 \_\_\_\_\_

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_  
 Execution Date May 16/25/29/30, June 1, and 2, 2000

Street Address: 7-35, Kitashinagawa 6- Chome  
Shinagawa-Ku  
 City: Tokyo, Japan State: \_\_\_\_\_ Zip: \_\_\_\_\_  
 Additional Name(s) & Address(es) attached  Yes  No

4. Application (number(s) or patent number(s):  
 If this document is being filed together with a new application, the execution date of the application is: May 16, 25, 29, 30, June 1 and 2, 2000

A. Patent Application No.(s)  
 Attorney Docket P00,0734

B: Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

**Hill & Simpson, P.C.**  
 85th Floor Sears Tower  
 233 S. Wacker Drive  
 Chicago, IL 60606

6. Total number of applications and patents involved  
 \_\_\_\_\_  
1

7. Total Fee (37 CFR 3.41) ..... \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account any Additional fees

8. Deposit Account Number:  
08-2290  
 (Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature:  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

John Simpson  
 Name of Person Signing

*John Simpson*  
 Signature

June 20, 2000  
 Date

Total number of pages comprising cover sheet: 4

Mail documents to be recorded and required cover sheet information to:  
**Commissioner of Patents and Trademarks**  
**Box Assignments**  
**Washington, D.C. 20231**

1571 U.S. PTO  
 09/590308  
 06/21/00

07/19/2000 JJMLLWZ 00000011 09598308

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**PATENT**  
**REEL: 010920 FRAME: 0612**

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in METHOD FOR PROCESSING THE SURFACE OF AN INSULATING ARTICLE,  
PRINTER HEAD AND SUBSTRATE FOR RECORDING MEDIUM  
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

SEIICHI WATANABE

Name of first or sole inventor

Execution date of U.S. Patent Application

TOKYO, JAPAN

Residence of first or sole inventor

*Seiichi Watanabe*

*June 2, 2008*  
*Seiichi Watanabe*

Signature of first or sole inventor

Date of this assignment

KENJI SHINOZAKI

May 29, 2000

Name of second inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of second inventor

Kenji Shinzaki

May 27, 2000

Signature of second inventor

Date of this assignment

MINORU KOHNO

May 16, 2000

Name of third inventor

Execution date of U.S. Patent Application

TOKYO, JAPAN

Residence of third inventor

Minoru Kohno

May 16, 2000

Signature of third inventor

Date of this assignment

HIROYUKI MITSUHASHI

May 25, 2000

Name of fourth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of fourth inventor

Hiroyuki Mitsuhashi

May 25, 2000

Signature of fourth inventor

Date of this assignment

MINEHIRO TONOSAKI

May 30, 2000

Name of fifth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of fifth inventor

Minehiro Tonosaki

May 30, 2000

Signature of fifth inventor

Date of this assignment

MASATO KOBAYASHI

June, 1, 2000

Name of sixth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of sixth inventor

*Masato Kobayashi*

June, 1, 2000

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment